

PATENT ABSTRACTS OF JAPAN

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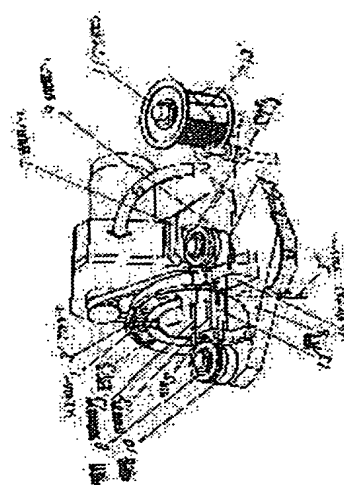
(54) METHOD FOR CUTTING AND REMOVING MASKING SHEET FOR PROCESSING SILICON WAFER

(57)Abstract:

PURPOSE: To automate the process for improving the productivity as well as for increasing the yield rate of wafers by successively paying out and contacting an energized heating wire with the outer periphery of a rotating wafer so as to cut away the out sheet portion, and thereafter successively paying out and contacting a non-energized wire with the outer periphery of the rotating wafer.

CONSTITUTION: Since a rocking plate 6 approaches in the direction of an arrow 6 to the outer periphery of a rotating silicon wafer 1, a heated energized heating wire 13 (heater wire) contacts therewith, so that the out sheet portion 3' of a masking sheet 3 is cut away along the outer periphery of the silicon wafer 1.

Further, since a non-energized wire 13' (dummy wire) which is not heated comes into contact with the portion under the energized heating wire 13, the out sheet 3' which has been cut off, and lumps or refuses of the sheet produced by the heating are surely separated from the silicon wafer 1, and the dust sheet 3" which has been cut off falls below. The angles between the silicon wafer 1 and the energized heating wire 13 and the non-energized wire 13' are somewhat wider than right angle at the outer periphery of the silicon wafer 1 with regard to the direction in which the wire is running.



LEGAL STATUS

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